



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2020-10-16
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	giovanni giacopello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STGIPQ5C60T-HZS	IW2U*RI62R5F	A	998G	2020-10-16
	Amount	UoM	Unit type	ST ECOPACK Grade
	4595	mg	Each	ECOPACK 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
Not Applicable	Not Applicable	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM00696723	



Package Designator	Size	Nbr of instances	Shape	
ZIP	32.15,12.45,4.00	26	Through-hole	
Comment	N2DIP-26L			

QueryList : RoHS Directive 2011/65/EU-July 2011 Annex II amended by Delegated Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2020/363_ March 2020	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.04	die	10
Lead	5.94	soft solder	1292

QueryList : REACH-25th June 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	5.94	Soft solder	1292
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	5.9382	Soft solder	900000

Responsible metals sourcing	
Query	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Gold, Tin,
This product is in the scope of the responsible metals sourcing, its compliance is covered by our company processes .	

Material Composition Declaration :						Mfr Item Name	IW2U*R162R5F					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Dies	M-011 Other inorganic materials	34.776	mg	supplier	die	Silicon(Si)	7440-21-3		33.737	mg	970123	7343
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.332	mg	9547	72
				supplier	metallisation	Chromium(Cr)	7440-47-3		0.002	mg	58	0
				supplier	metallisation	Gold(Au)	7440-57-5		0.007	mg	201	2
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.044	mg	1265	10
				supplier	metallisation	Silver(Ag)	7440-22-4		0.007	mg	201	2
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.002	mg	58	0
				supplier	metallisation	Vanadium(V)	7440-62-2		0.001	mg	29	0
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.199	mg	5722	43
				supplier	passivation	Silicon oxide	7631-86-9		0.344	mg	9892	75
Leadframe	M-004 Copper and its alloys	1640.039	mg	supplier	polymer coating	Durimide	proprietary		0.101	mg	2904	22
				supplier	alloy & coating	Copper(Cu)	7440-50-8		1592.478	mg	971000	346568
				supplier	alloy & coating	Iron(Fe)	7439-89-6		34.441	mg	21000	7495
				supplier	alloy & coating	Phosphorus metal	7723-14-0		1.640	mg	1000	357
				supplier	alloy & coating	Zinc(Zn)	7440-66-6		1.640	mg	1000	357
NTC	M-011 Other inorganic materials	0.283	mg	supplier	alloy & coating	Silver (Ag)	7440-22-4		9.840	mg	6000	2141
				supplier	die	Silicon(Si)	7440-21-3		0.283	mg	1000000	62
Die attach	M-011 Other inorganic materials	2.018	mg	supplier	glue	Silver(Ag)	7440-22-4		1.616	mg	800793	352
				supplier	glue	High boiling methacrylate	Proprietary		0.202	mg	100099	44
				supplier	glue	Polybutadiene diacrylate	Proprietary		0.101	mg	50050	22
				supplier	glue	Silica, amorphous, treated	68909-20-6		0.097	mg	48067	21
Soft solder	Solder	6.598	mg	SVHC	solder	Lead (Pb)	7439-92-1	7a-Lead in high melting temper	5.938	mg	900000	1292
				supplier	solder	Tin (Sn)	7440-31-5		0.660	mg	100000	144
				supplier	wire	Gold (Au)	7440-57-5		4.744	mg	1000000	1032
Encapsulation	M-011 Other inorganic materials	2885.610	mg	supplier	mold compound	Crystalline Silica	14808-60-7		1679.425	mg	582000	365490
				supplier	mold compound	Fused Silica	60676-86-0		432.842	mg	150000	94198
				supplier	mold compound	polyglycidyl ether ocresoformaldehyde novol	29690-82-2		288.561	mg	100000	62799
				supplier	mold compound	Phenolic resin	9003-35-4		230.849	mg	80000	50239
				supplier	mold compound	Aluminium Hydroxide	21645-51-2		230.849	mg	80000	50239
connections coating	Solder	20.932	mg	supplier	mold compound	Carbon black	1333-86-4		23.084	mg	8000	5024
				supplier	solder alloy	Tin (Sn)	7440-31-5		20.932	mg	1000000	4555